

Dowton Electronic Materials Co.,Ltd.

Copper Paste (Cu Paste)

Introduction

1. This series is designed for MLCC process and the development of the outer electrode conductive paste.
2. Excellent coverage and appearance
3. In line with REACH and ROHS specifications, lead and cadmium free.



Product Benefits

1. Has excellent adhesive properties, preventing the end from peeling.
2. Excellent mechanical strength and reliability.
3. High dense fired film, preventing the infiltration leakage of plating.

Composition Properties & Usage Requirements

Product	Type (°C @N ₂)	S.C.%	Vis., pa.s, 10rpm
PF-80504	790~820	78	40
PF-90428	900~930	76	60
PF-90428C	720~780	76	55
PF-90428D	680~750	76	55
MLC-90851	750	85	76
MLC-90852	900	85	76
MLC-7501	750	77	76

Additional Information

1. The above are the typical properties, due to individual requirements, the represented data above is not intended to be used as specification limits.
2. Viscosity measurements were made using Brookfield DV-III +, SC4-14 / 6R, 25 ° C.
3. Please refer your attention to all relevant safety labels.
4. Please stir, and make sure a proper mixture before use.
5. Shelf Life: Maximum 6 months with proper storage.
6. Storage conditions: RH<85% , temperature 5~25°C.